

UTT80N06H

Power MOSFET

60V, 80A N-CHANNEL
POWER MOSFET

■ DESCRIPTION

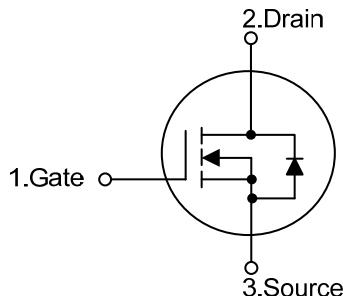
The UTC **UTT80N06H** is a N-channel enhancement mode power MOSFET using UTC's advanced technology to provide customers with a minimum on-state resistance and high switching speed. It can also withstand high energy pulse in the avalanche and commutation mode.

The UTC **UTT80N06H** is suitable for active power factor correction, high efficient switched mode power supplies and electronic lamp ballast based on half bridge topology, etc.

■ FEATURES

- * $R_{DS(ON)} \leq 6.5 \text{ m}\Omega$ @ $V_{GS}=10\text{V}$, $I_D=40\text{A}$
- * High switching speed
- * Improved dv/dt capability

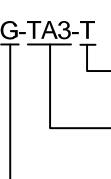
■ SYMBOL



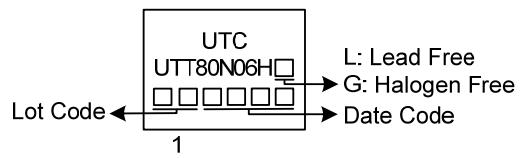
■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
UTT80N06HL-TA3-T	UTT80N06HG-TA3-T	TO-220	G	D	S	Tube
UTT80N06HL-TN3-R	UTT80N06HG-TN3-R	TO-252	G	D	S	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source

 (1)Packing Type (2)Package Type (3)Green Package	(1) T: Tube, R: Tape Reel (2) TA3: TO-220, TN3: TO-252 (3) G: Halogen Free and Lead Free L: Lead Free
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■ 4MARKING



■ ABSOLUTE MAXIMUM RATINGS ($T_c = 25^\circ\text{C}$, unless otherwise specified) (Note 2)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	60	V
Gate-Source Voltage		V_{GSS}	± 20	V
Drain Current	Continuous	$T_c = 25^\circ\text{C}$	I_D	80
		$T_c = 100^\circ\text{C}$		48
	Pulsed (Note 2)		I_{DM}	160
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	92	mJ
Peak Diode Recovery dV/dt (Note 4)		dV/dt	2.6	V/nS
Power Dissipation	TO-220	P_D	147	W
	TO-252		58	W
Junction Temperature		T_J	+150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 ~ +150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.
 Absolute maximum ratings are stress ratings only and functional device operation is not implied.
 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
 3. $L = 0.1\text{mH}$, $I_{AS} = 42\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$.
 4. $I_{SD} \leq 30\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$.

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-220	θ_{JA}	62.5	$^\circ\text{C/W}$
	TO-252		110	$^\circ\text{C/W}$
Junction to Case	TO-220	θ_{JC}	0.85	$^\circ\text{C/W}$
	TO-252		2.2 (Note)	$^\circ\text{C/W}$

Note: Device mounted on FR-4 substrate P_C board, 2oz copper, with 1inch square copper plate.

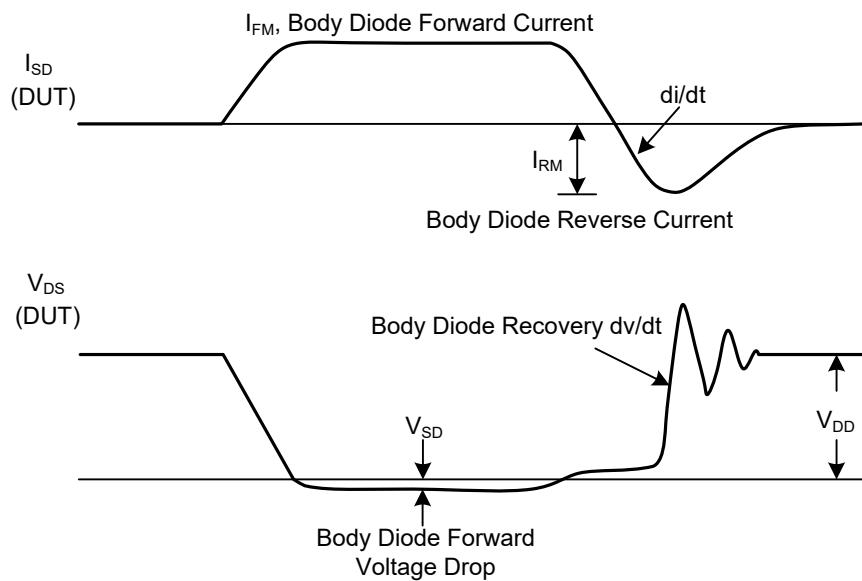
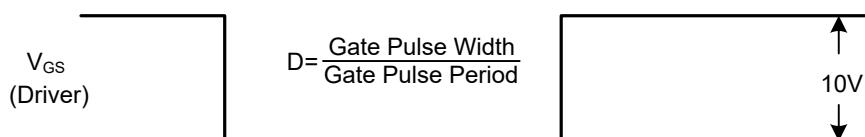
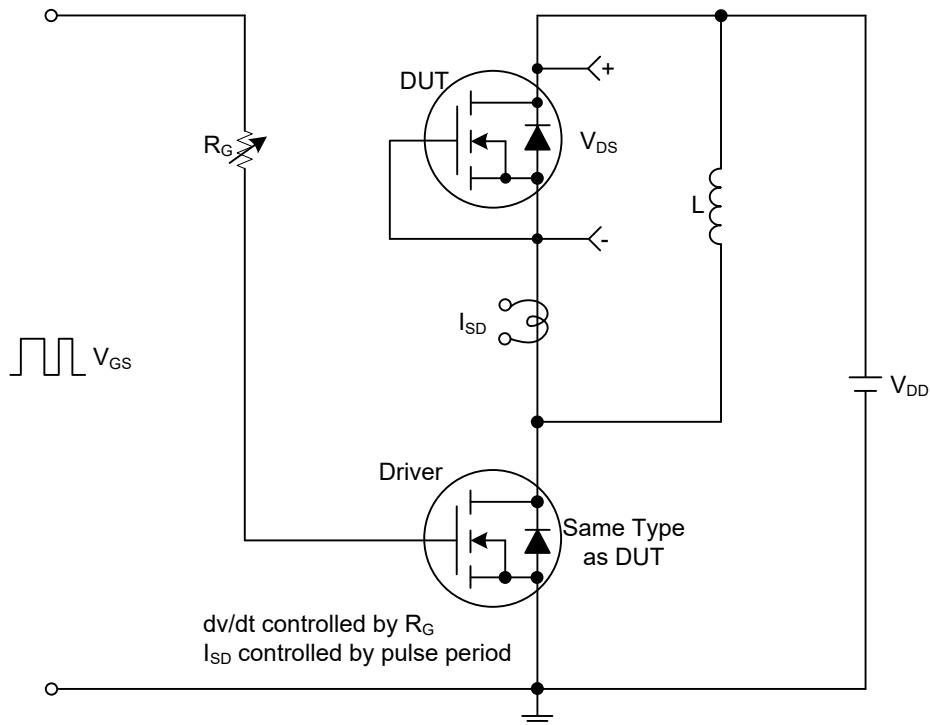
■ ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D=250\mu\text{A}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$	60			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=60\text{V}, V_{GS}=0\text{V}$			1	μA
Gate-Source Leakage Current	Forward I_{GSS}	$V_{GS}=+20\text{V}, V_{DS}=0\text{V}$			+100	nA
	Reverse I_{GSS}	$V_{GS}=-20\text{V}, V_{DS}=0\text{V}$			-100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(\text{TH})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.0		4.0	V
Static Drain-Source On-State Resistance	$R_{DS(\text{ON})}$	$V_{GS}=10\text{V}, I_D=40\text{A}$			6.5	$\text{m}\Omega$
DYNAMIC PARAMETERS						
Input Capacitance	C_{ISS}	$V_{GS}=0\text{V}, V_{DS}=25\text{V}, f=1.0\text{MHz}$		4000		pF
Output Capacitance	C_{OSS}			400		pF
Reverse Transfer Capacitance	C_{RSS}			320		pF
SWITCHING PARAMETERS						
Total Gate Charge at 10V	Q_G	$V_{DS}=48\text{V}, V_{GS}=10\text{V}, I_D=80\text{A}$ (Note 1, 2)		103		nC
Gate to Source Charge	Q_{GS}			19		nC
Gate to Drain Charge	Q_{GD}			41		nC
Turn-ON Delay Time	$t_{D(\text{ON})}$	$V_{DS}=30\text{V}, V_{GS}=10\text{V}, I_D=80\text{A}, R_G=3.3\Omega$ (Note 1, 2)		16		ns
Rise Time	t_R			20		ns
Turn-OFF Delay Time	$t_{D(\text{OFF})}$			50		ns
Fall-Time	t_F			27		ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Maximum Body-Diode Continuous Current	I_S				80	A
Maximum Body-Diode Pulsed Current	I_{SM}				160	A
Drain-Source Diode Forward Voltage	V_{SD}	$I_S=80\text{A}, V_{GS}=0\text{V}$			1.4	V
Reverse Recovery Time	t_{rr}	$I_S=30\text{A}, V_{GS}=0\text{V}, dI/dt=100\text{A}/\mu\text{s}$		60		nS
Reverse Recovery Charge	Q_{rr}			61		nC

Notes: 1. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$.

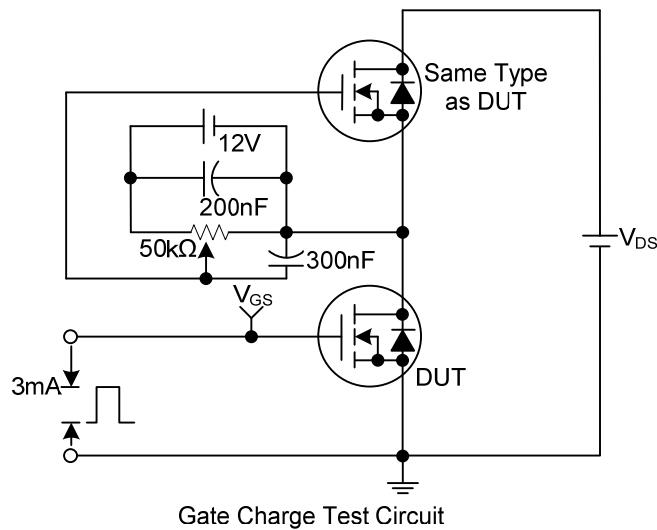
2. Essentially independent of operating temperature typical characteristics.

■ TEST CIRCUITS AND WAVEFORMS

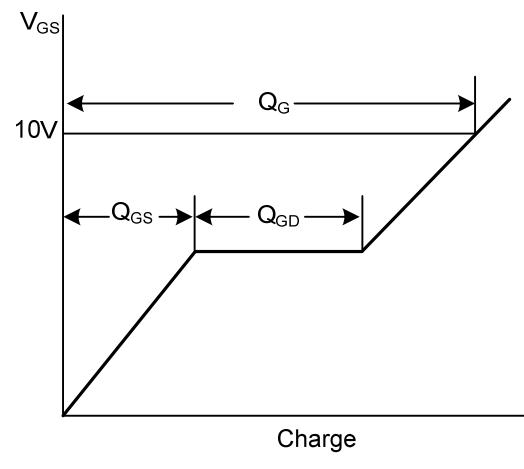


Peak Diode Recovery dv/dt Test Circuit and Waveforms

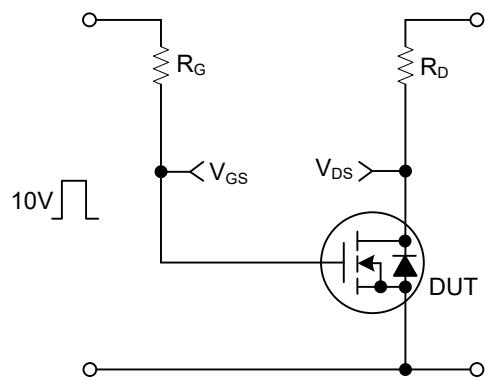
■ TEST CIRCUITS AND WAVEFORMS



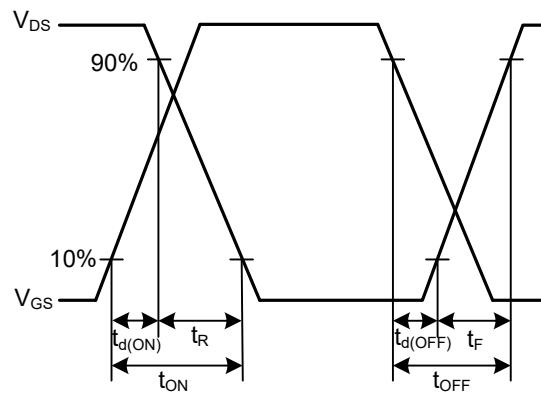
Gate Charge Test Circuit



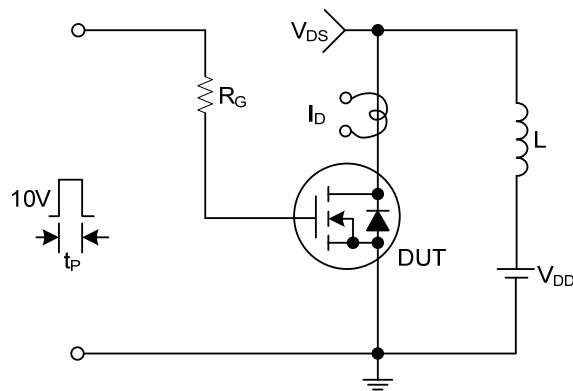
Gate Charge Waveforms



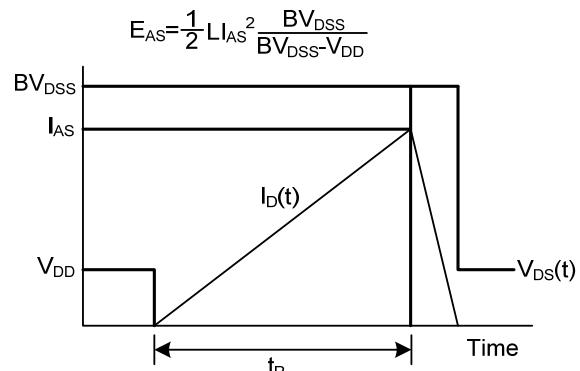
Resistive Switching Test Circuit



Resistive Switching Waveforms

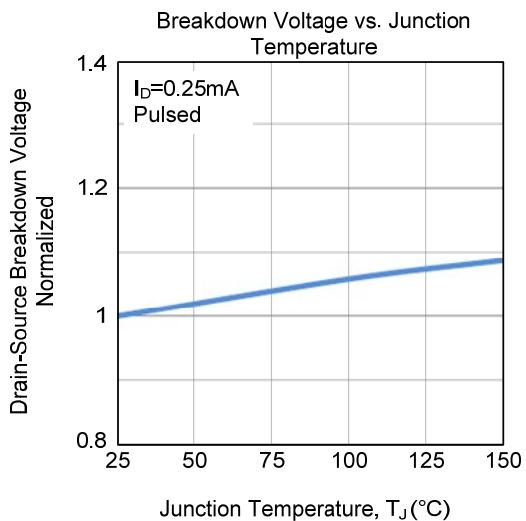
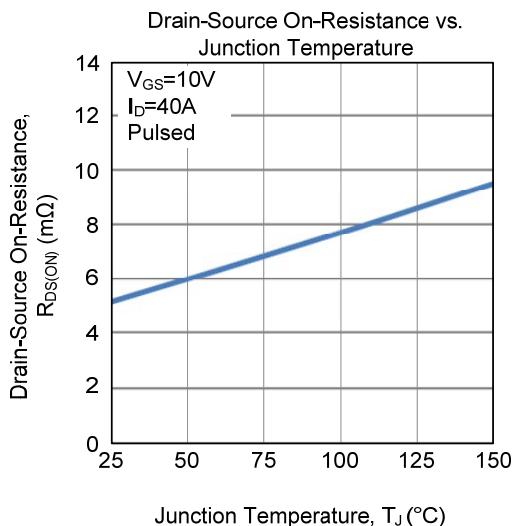
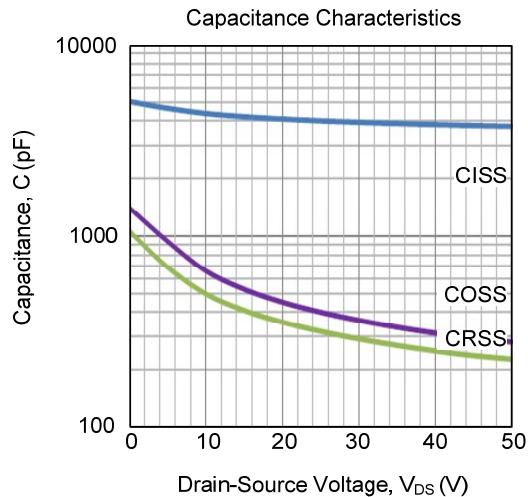
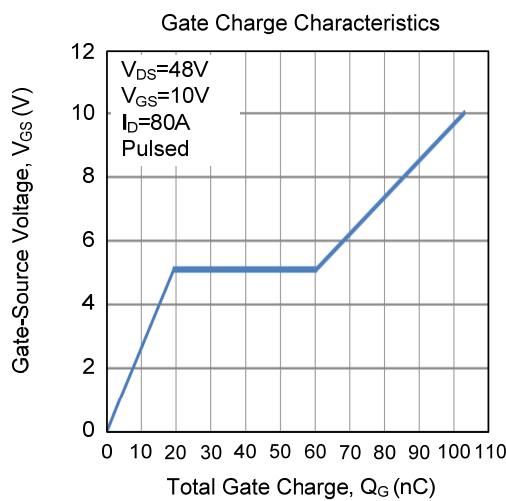
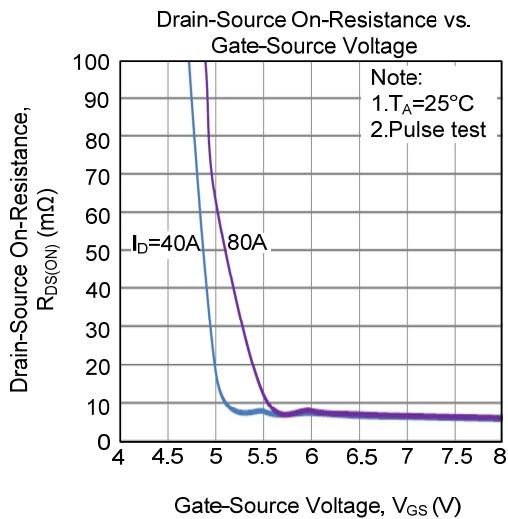
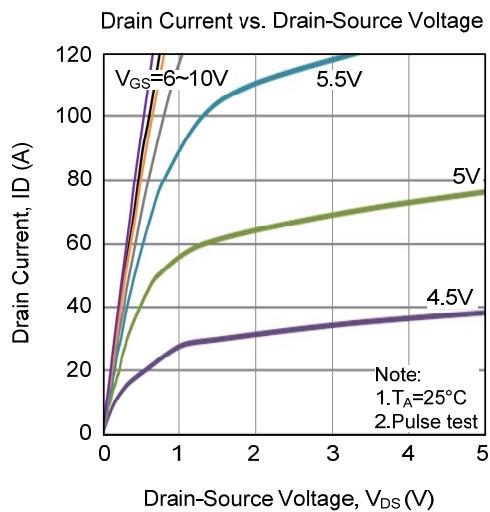


Unclamped Inductive Switching Test Circuit

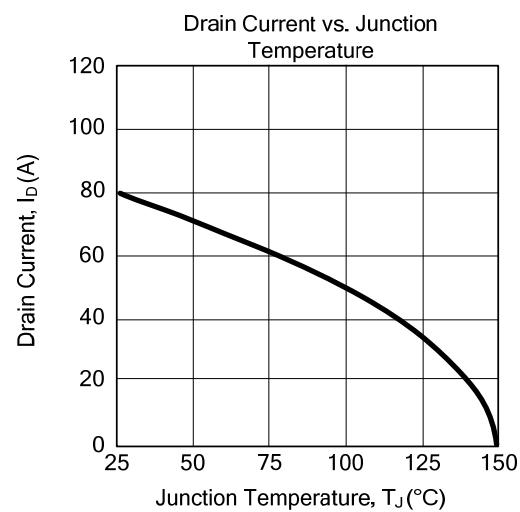
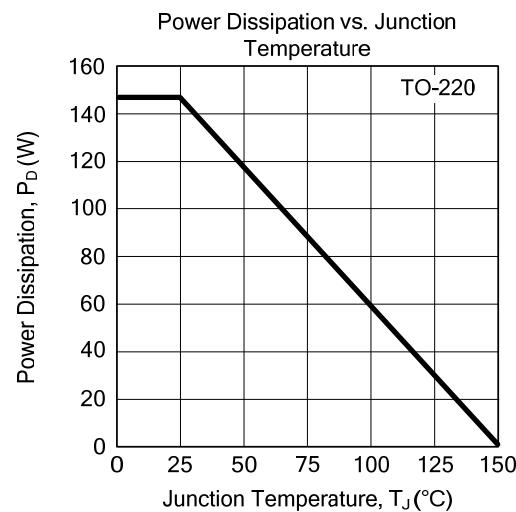
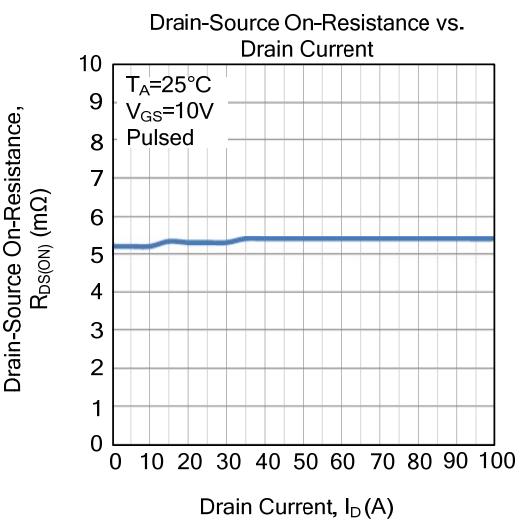
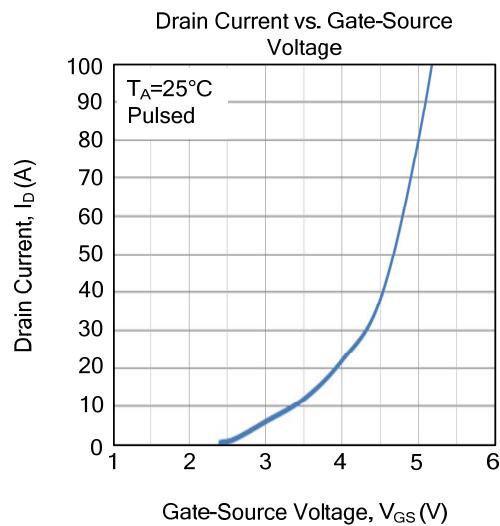
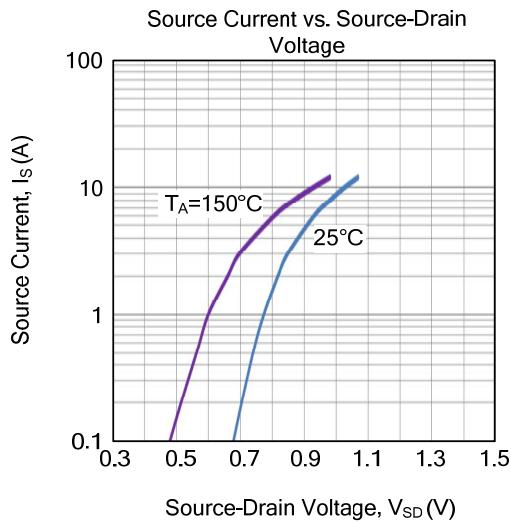
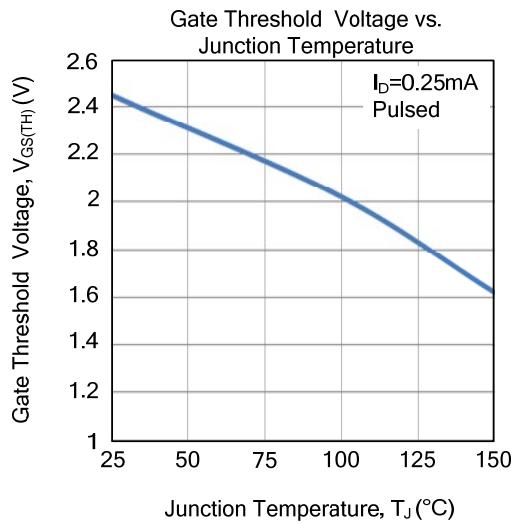


Unclamped Inductive Switching Waveforms

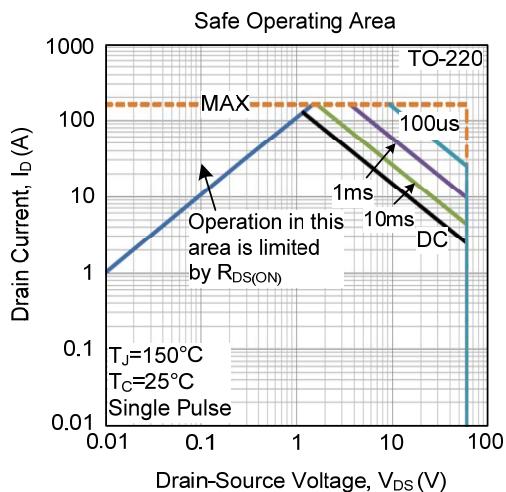
■ TYPICAL CHARACTERISTICS



■ TYPICAL CHARACTERISTICS (Cont.)



■ TYPICAL CHARACTERISTICS (Cont.)



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